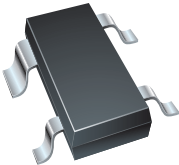


MATERIAL DECLARATION SHEET



Material Number	CD143A-SR05LC			
Product Line	Semiconductor Products			
Compliance Date	2008/7/13			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.34400	Silicon	7440-21-3	100.00%	3.066%	3.066%
2	Lead frame	Copper Alloy	0.03032	Nickel	7440-02-0	0.80%	0.270%	33.782%
			0.04548	Tin	7440-31-5	1.20%	0.405%	
			0.00265	Phosphorus	7723-14-0	0.07%	0.024%	
			3.67365	Copper	7440-50-8	96.93%	32.745%	
			0.03790	Silver	7440-22-4	1.00%	0.338%	
3	Epoxy	Polymer	0.17500	Silicon dioxide Quartz	14808-60-7	50.00%	1.560%	3.12%
			0.10500	Epoxy resin	Proprietary	30.00%	0.936%	
			0.01050	Aromatic Amine	Proprietary	3.00%	0.094%	
			0.05950	Epoxy resin modifier	Proprietary	17.00%	0.530%	
4	Cu Wire	Noble metal	0.02157	Copper	7440-50-8	98.08%	0.192%	0.1962%
			0.00040	Palladium	7440-05-3	1.80%	0.004%	
			0.00003	Gold	7440-57-5	0.12%	0.0002%	
5	Mold Compound	Polymer	5.18880	Silica	60676-86-0	80.00%	46.2508%	57.8128%
			0.64860	Epoxy Resin	Trade Secret	10.00%	5.781%	

MATERIAL DECLARATION SHEET



			0.62914	Phenolic Resin	Trade Secret	9.70%	5.608%	
			0.01946	Carbon Black	1333-86-4	0.30%	0.173%	
6	Plating	Plating	0.22677	Tin	7440-31-5	99.90%	2.021%	2.023%
			0.00023	Misc., not to declare	N/A	0.10%	0.002%	
		Total weight	11.219 mg					

This Document was updated on: 2017/3/13

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.